

WF6033
Water Soluble Liquid Flux

Product Description

WF6033, Asahi's water soluble liquid flux exhibits fluxing ability that shows excellent capillary action on plated through-holes and also reducing solder bridging. The neutral chemistry of this flux is neither acidic nor alkaline. This is an important factor related directly to the reliability and high speed soldering and cleaning of printed circuit assemblies. This flux does not attack properly cured solder masks or FR-4 epoxy glass laminate.

Application

WF6033 is specially formulated for spraying, foaming and dipping process. Recommended on-board preheat temperature is about 80 - 90°C. This flux is compatible with both SnPb and lead free solders.

Residue Removal

Flux residue can be removed by plain water at 60 +/- 5 °C. Washing of the PCB when soldered with WF6033 should be done within 4 hours time length.

Recommended Solvent

Asahi's complementary Solvent #3000. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, WF6033 can be stored for up to 6 months. WF6033 is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

Packaging

Available in 20kg/carboy.

Specification

Item	Result
State	Liquid
Colour	Pale yellow
Specific Gravity @ 25°C	0.860 +/- 0.005
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 3hr)	20.5 +/- 2.0 wt%
<small>IPC-TM-650 2.3.34</small>	
<small>JIS Z 3197 8.1.3</small>	
Halide Content	2.0 +/- 0.2 wt%
<small>JIS Z 3197 8.1.4.2.1</small>	
Acid Value Test	46 +/- 4 mg KOH/g flux
<small>IPC-TM-650 2.3.13</small>	
<small>JIS Z 3197 8.1.4.1</small>	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 ⁸ Ω, Pass
<small>IPC-TM-650 2.6.3.3</small>	
<small>JIS Z 3197 8.5.3</small>	> 1 x 10 ¹¹ Ω, Pass
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
<small>IPC-TM-650 2.6.14.1</small>	
Copper Corrosion Test	Pass
<small>IPC-TM-650 2.6.15</small>	
<small>JIS Z 3197 8.4.1</small>	
Copper Mirror Test	Classified as "H", Pass
<small>IPC-TM-650 2.3.32</small>	
<small>JIS Z 3197 8.4.2</small>	
Flux Activity Classification	ROH1
<small>IPC J-STD-004</small>	
pH	6.5 +/- 1
Flash Point	16°C
Spread Factor	> 80% (SnPb)
<small>JIS Z 3197 8.3.1.1</small>	

DISCLAIMER OF LIABILITY

"All statements, information and recommendations contained in this catalog are based on data and test results which we consider, to the best of our knowledge and belief, to be reliable and informative to the users but the accuracy and completeness thereof is not guaranteed. No warranty, expressed or implied, statutory or otherwise, is given regarding the use of the information and products contained in this catalog since the conditions and suitability for use, handlings, storage or possession of the products are determined by the users and are therefore beyond our control. We shall not be liable in respect of any liabilities, losses (including consequential losses), damages, proceedings, costs, claims or injuries whatsoever sustained or suffered by the users (including any third parties) in connection with the use of the information, recommendation and the products contained in this catalog."

Singapore Asahi Chemical and Solder Industries Pte Ltd

47 Pandan Road Singapore 609288

Tel: +65 6262-1616 Fax: +65 6261-6311

 Website: <http://www.asahisolder.com> Email: enquiry@sinasahi.com.sg